

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>JinGwan Kim</td> <td>03/22/2011</td> </tr> <tr> <td>KyuWon Lee</td> <td>03/22/2011</td> </tr> <tr> <td>JiHoon Oh</td> <td>03/22/2011</td> </tr> <tr> <td>JongVin Park</td> <td>03/22/2011</td> </tr> </tbody> </table>		Name	Execution Date	JinGwan Kim	03/22/2011	KyuWon Lee	03/22/2011	JiHoon Oh	03/22/2011	JongVin Park	03/22/2011
Name	Execution Date										
JinGwan Kim	03/22/2011										
KyuWon Lee	03/22/2011										
JiHoon Oh	03/22/2011										
JongVin Park	03/22/2011										
RECEIVING PARTY DATA											
Name:	STATS ChipPAC Ltd.										
Street Address:	10 Ang Mo Kio Street 65										
Internal Address:	#05-17/20 Techpoint										
City:	Singapore										
State/Country:	SINGAPORE										
Postal Code:	569059										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13070219</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13070219						
Property Type	Number										
Application Number:	13070219										
CORRESPONDENCE DATA											
Fax Number:	(408)738-0881										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	408-738-0592										
Email:	efiling@ishimarulaw.com										
Correspondent Name:	LAW OFFICES OF MIKIO ISHIMARU										
Address Line 1:	333 W. EL CAMINO REAL										
Address Line 2:	SUITE 330										
Address Line 4:	SUNNYVALE, CALIFORNIA 94087										
ATTORNEY DOCKET NUMBER:	27-659										
NAME OF SUBMITTER:	Mikio Ishimaru										
Total Attachments: 3 source=27-659_Assignment#page1.tif source=27-659_Assignment#page2.tif source=27-659_Assignment#page3.tif											

CH \$40.00 13070219

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH EMBEDDED CONDUCTIVE STRUCTURE AND METHOD OF MANUFACTURE THEREOF

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee(s), the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee(s), the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee(s) where said Assignee(s) may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee(s).
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee(s), its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

5. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 13/070,219 Filing Date: March 23, 2011

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Jin Gwan Kim
JinGwan Kim

22 / 03 / 2011
Date

[Signature]
Witness Signature

[Signature]
Witness Signature

Choi Daesik
Print Witness Name

Lee Hyung Min
Print Witness Name

Mar-22-2011
Date

Mar 22 '11
Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

[Signature]
KyuWon Lee

22 / 03 / 2011
Date

[Signature]
Witness Signature

[Signature]
Witness Signature

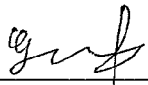
Choi Daesik
Print Witness Name

Lee Hyung Min
Print Witness Name

Mar-22-2011
Date

Mar 22 '11
Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



JiHoon Oh

Mar - 22 - '11

Date



Witness Signature



Witness Signature

Choi DaeSik

Print Witness Name

Lee Hyung Min

Print Witness Name

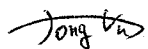
Mar-22-2011

Date

Mar. 22 '11

Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



JongVin Park

22 / 03 / '11

Date



Witness Signature



Witness Signature

Choi DaeSik

Print Witness Name

Lee Hyung Min

Print Witness Name

Mar-22-2011

Date

Mar. 22 '11

Date